# CPI0806J3R3R-10

## UNCONTROLLED DOCUMENT

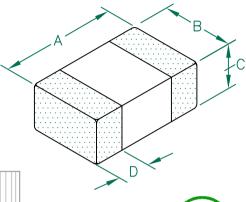
#### PHYSICAL DIMENSIONS:

A 2.00 [.079] ± 0.15[.006]

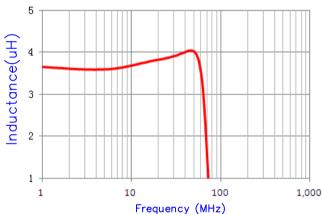
B 1.60 [.063] ± 0.15[.006]

C 0.90 [.035] ± 0.10[.004]

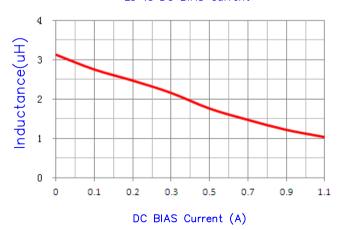
D 0.50 [.020] ± 0.20[.008]



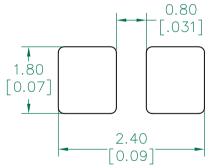




Ls vs DC BIAS Current



### LAND PATTERNS FOR REFLOW SOLDERING



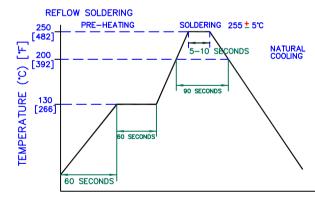
(For wave soldering. add 0.763 [0.030] to this dimension)

	ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR ( $\frac{\Omega}{2}$ ) ± 30%	l (Max)							
Nom	3.30	0.240								
Min	2.64	0.168								
Max	3.96	0.312	1100mA							

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

#### RECOMMENDED SOLDERING CONDITIONS





	DIMENSIONS ARE IN mm [INCHES]. This print is the property of Lai										
					Tech, and is loaned in confidence subject to return upon request of		Laird				
					with the understanding that no						
l					copies shall be made without the written consent of Laird Tech. Al	B 					
					rights to design or invention are						
1					reserved.						
					PROJECT/PART NUMBER:	RE	٧	PART TO	PE:	DRAWN BY:	
					CPI0806J3R3R-10		В	co-	-FIRE	QU	
i	В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11 S	SCALE:	NI.	L	SHEET:		
	Α	ORIGINAL DRAFT	03/01/11	QU	, ,		NTS		_		
i	REV	DESCRIPTION	DATE	INT		100L §	٠.	-	2	of 2	